

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc3703egn-5#trpbf

(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.081976**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003116	1000000	38011.09375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.029933	975000	365143.15625		
		Iron (Fe)	7439-89-6	0.000737	24000	8990.42871094		
		Phosphorus (P)	7723-14-0	0.000009	300	109.788139343		
		Zinc (Zn)	7440-66-6	0.000021	700	256.172332764		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.030700</b>	<b>1000000</b>	<b>374499.53125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002272	1000000	27716.3828125		
		<b>External Plating Total:</b>				<b>0.002272</b>	<b>1000000</b>	<b>27716.3828125</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000246	1000000	3000.87597656		
<b>Internal Plating Total:</b>				<b>0.000246</b>	<b>1000000</b>	<b>3000.87597656</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000926	750000	11295.9794922		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000309	250000	3769.39257812		
<b>Die Attach Total:</b>				<b>0.001235</b>	<b>1000000</b>	<b>15065.3720703</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004547	103000	55467.40625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.039514	895000	482018.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000088	2000	1073.48400879		
		<b>Encapsulation Total:</b>				<b>0.044149</b>	<b>1000000</b>	<b>538559.625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000258	1000000	3147.25976562		
					<b>TOTAL MASS (g) :</b>	<b>0.081976</b>		